ABSTRACT

DUAL ROW LEADFRAME AND FABRICATION METHOD

A semiconductor package is provided. A leadframe including a die attach paddle, a number of inner leads, and a number of outer leads, and a number of extended lead tips on the number of outer leads. The inner edges of the number of extended lead tips are in substantial alignment with the inner edges of the number of inner leads. A die is attached to the die attach paddle. A number of bonding wires is used to connect the die to the number of inner leads and the extended lead tips on the number of outer leads, and an encapsulant is formed over the leadframe and the die. (Fig. 1)